

Docket No. 215899US90PCT



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Yasuji HIRAMATSU, et al.

SERIAL NO: 09/926,499

GAU: 1772

RCE FILED: November 17, 2003

EXAMINER: Jane J. Rhee

FOR: CERAMIC SUBSTRATE

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97

COMMISSIONER FOR PATENTS  
ALEXANDRIA, VIRGINIA 22313

SIR:

Applicant(s) wish to disclose the following information.

REFERENCES

- ☒ The applicant(s) wish to make of record the references listed on the attached form PTO-1449. Copies of the listed references are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.
- ☐ A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

RELATED CASES

- ☒ Attached is a list of applicant's pending application(s) or issued patent(s) which may be related to the present application. A copy of the patent(s), together with a copy of the claims and drawings of the pending application(s) is attached along with PTO 1449.
- ☒ A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

CERTIFICATION

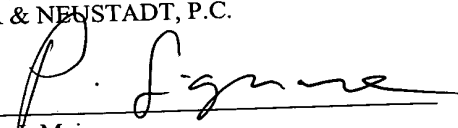
- ☐ Each item of information contained in this information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- ☐ No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

DEPOSIT ACCOUNT

- ☒ Please charge any additional fees for the papers being filed herewith and for which no check or credit card payment is enclosed herewith, or credit any overpayment to deposit account number 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

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Form PTO 1449  
(Modified)U.S. DEPARTMENT OF COMMERCE  
PATENT AND TRADEMARK OFFICEATTY DOCKET NO.  
215899US90PCTSERIAL NO.  
09/926,499

## LIST OF REFERENCES CITED BY APPLICANT

APPLICANT

Yasuji HIRAMATSU, et al.

RCE FILING DATE  
November 17, 2003GROUP  
1772

## U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	AA	2003/0054147	03/20/03	Niwa			
	AB	2003/0015521	01/23/03	Ito			
	AC	6,507,006	01/14/03	Hiramatsu et al.			
	AD	6,465,763	10/15/02	Ito et al.			
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	AF	5,229,549	07/20/93	Yamakawa et al.			
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	AI	6,731,496	05/04/04	Hiramatsu et al.			
	AJ	6,710,307	03/23/04	Ito et al.			
	AK						
	AL						
	AM						
	AN						

## FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION	
					YES	NO
	AO	1 225 157	07/24/02	Europe (in English language)		
	AP	1 225 790	07/24/02	Europe (in English language)		
	AQ	0 963 137	12/08/99	Europe (in English language)		
	AR	0 771 772	05/07/97	Europe (in English language)		
	AS	1 109 423	06/20/01	Europe (in English language)		
	AT	7-126070	05/16/95	Japan (with English abstract)		X
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## OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)

	AW	Akio Igawa, "The Present Situation and Problems of Helium Leak Detector", Semiconductor World, November 1992, pages 111-115 (in Japanese, translation attached)
	AX	
	AY	
	AZ	

☐ Additional References sheet(s) attached

Date Considered

Examiner

\*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.



**LIST OF RELATED CASES**

<u>Docket Number</u>	<u>Serial or Patent Number</u>	<u>Filing or Issue Date</u>	<u>Inventor/ Applicant</u>
PER CLIENT	10/345,356	01/16/03	ITO
PER CLIENT	10/182,009	07/24/02	ZHOU
PER CLIENT	10/222,928	08/19/02	ITO
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\*Present Application; listed for information

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\*Present Application; listed for information

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